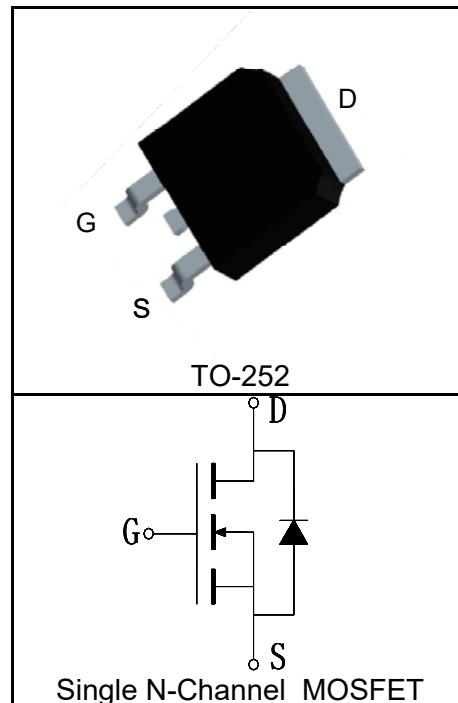


Features

- 200V/9A,
- $R_{DS\ (ON)} = 250\text{m}\Omega$ (Typ.)@ $V_{GS}=10\text{V}$
- Low $R_{DS\ (ON)}$
- Improved dv/dt Capability
- Reliable and Rugged

Pin Description



Applications

- Switch Mode Power Supply
- Uninterruptible Power Supply
- Power Factor Correction



Halogen-Free

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
Common Ratings ($T_C=25^\circ\text{C}$ Unless Otherwise Noted)			
V_{DSS}	Drain-Source Voltage	200	V
V_{GSS}	Gate-Source Voltage	± 20	
T_J	Maximum Junction Temperature	175	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ\text{C}$
I_S	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	A
Mounted on Large Heat Sink			
$I_{DP}^{(1)}$	300 μs Pulse Drain Current Tested	$T_C=25^\circ\text{C}$	36
$I_D^{(2)}$	Continuous Drain Current($V_{GS}=10\text{V}$)	$T_C=25^\circ\text{C}$	9
		$T_C=100^\circ\text{C}$	6
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	50
		$T_C=100^\circ\text{C}$	25
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3	$^\circ\text{C/W}$
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	100	$^\circ\text{C/W}$
Drain-Source Avalanche Ratings			
$E_{AS}^{(4)}$	Avalanche Energy, Single Pulsed	100	mJ

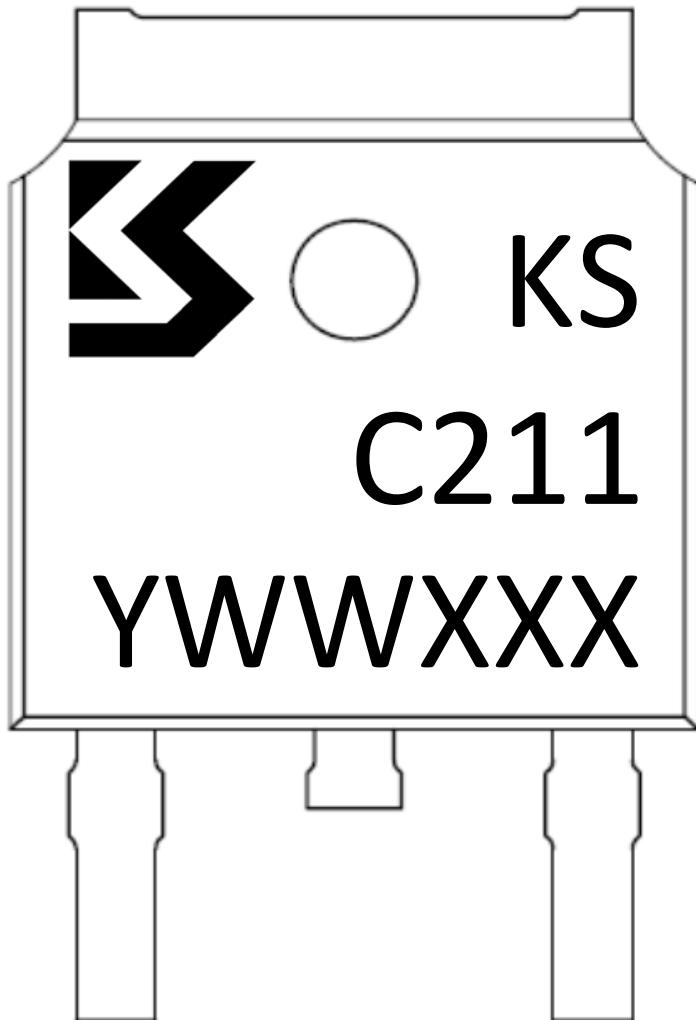
Electrical Characteristics ($T_C=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	KSC211DA			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{DS}}=250\mu\text{A}$	200			V
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=200\text{V}, \text{V}_{\text{GS}}=0\text{V}$			5	μA
		$\text{T}_J=125^\circ\text{C}$			100	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_{\text{DS}}=250\mu\text{A}$	2	3	4	V
I_{GSS}	Gate Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$			± 100	nA
$\text{R}_{\text{DS(ON)}}^{(5)}$	Drain-Source On-state Resistance	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_{\text{DS}}=5\text{A}$		250	300	$\text{m}\Omega$
Diode Characteristics						
$\text{V}_{\text{SD}}^{(5)}$	Diode Forward Voltage	$\text{I}_{\text{SD}}=9\text{A}, \text{V}_{\text{GS}}=0\text{V}$		0.9	1.4	V
t_{rr}	Reverse Recovery Time	$\text{I}_{\text{SD}}=5\text{A}, \frac{d\text{I}_{\text{SD}}}{dt}=100\text{A}/\mu\text{s}$		190		ns
Q_{rr}	Reverse Recovery Charge			1700		nC
Dynamic Characteristics ⁽⁶⁾						
R_G	Gate Resistance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=0\text{V}, \text{F}=1\text{MHz}$		1.2		Ω
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=100\text{V}, \text{Frequency}=1.0\text{MHz}$		685		pF
C_{oss}	Output Capacitance			105		
C_{rss}	Reverse Transfer Capacitance			40		
$\text{t}_{\text{d(ON)}}$	Turn-on Delay Time	$\text{V}_{\text{DD}}=100\text{V}, \text{I}_{\text{DS}}=9\text{A}, \text{V}_{\text{GEN}}=10\text{V}, \text{R}_G=6\Omega$		12		ns
t_r	Turn-on Rise Time			22		
$\text{t}_{\text{d(OFF)}}$	Turn-off Delay Time			50		
t_f	Turn-off Fall Time			48		
Gate Charge Characteristics ⁽⁶⁾						
Q_g	Total Gate Charge	$\text{V}_{\text{DS}}=100\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{I}_{\text{DS}}=9\text{A}$		23		nC
Q_{gs}	Gate-Source Charge			2.5		
Q_{gd}	Gate-Drain Charge			10		

- Notes:
- ①Pulse width limited by safe operating area.
 - ②Calculated continuous current based on maximum allowable junction temperature.
 - ③When mounted on 1 inch square copper board, $t \leq 10\text{sec}$. The value in any given application depends on the user's specific board design.
 - ④Limited by $T_{J\text{max}}, I_{AS} = 20\text{A}, L = 0.5\text{mH}, V_{DD} = 48\text{V}, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$.
 - ⑤Pulse test; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
 - ⑥Guaranteed by design, not subject to production testing.

Ordering and Marking Information

Device	Package	Packaging	Quantity	Reel Size	Tape width
KSC211DA	TO-252	Tape&Reel	2500	13"	16mm

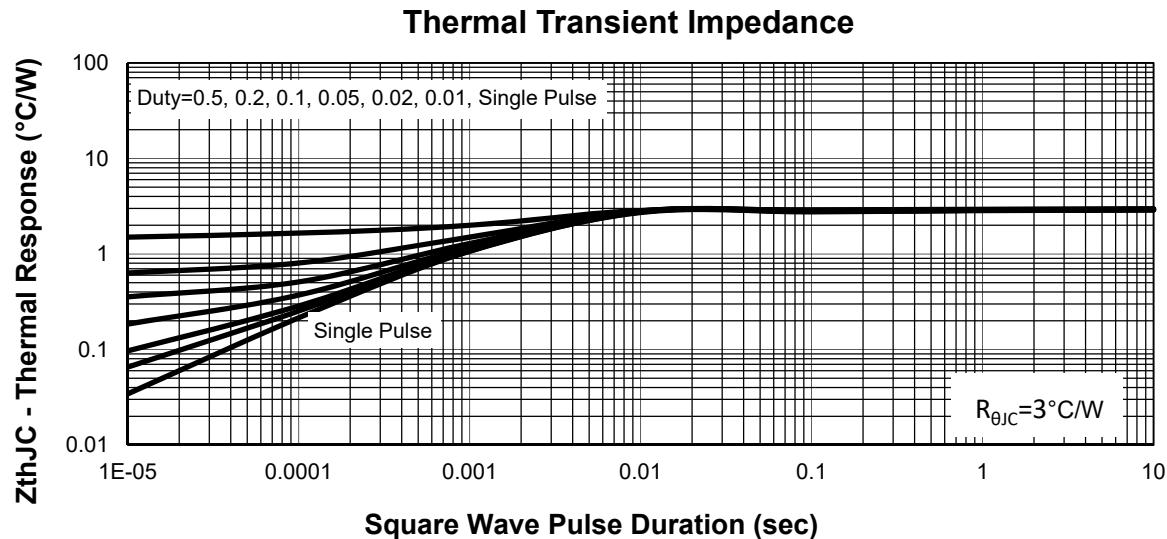
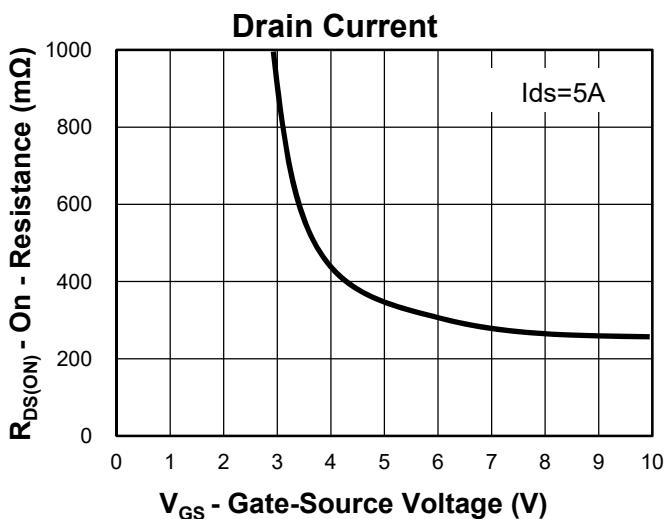
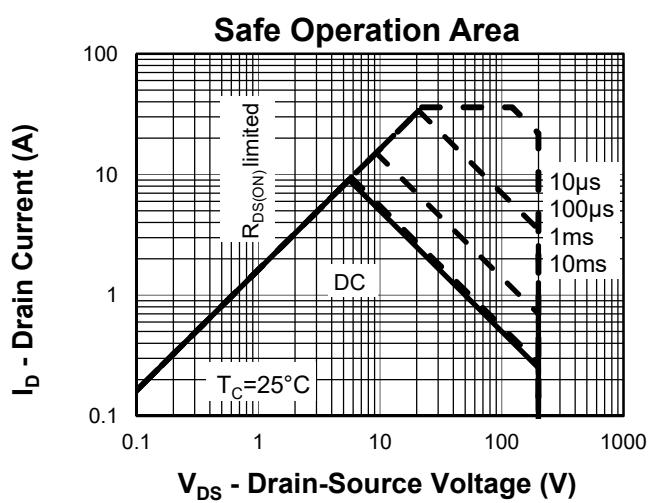
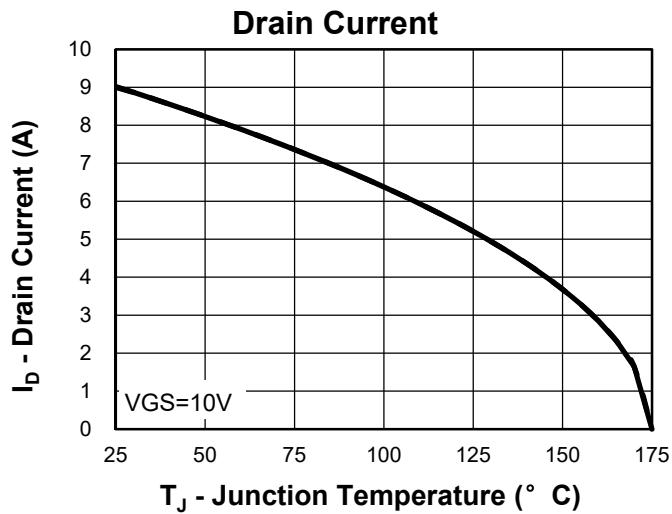
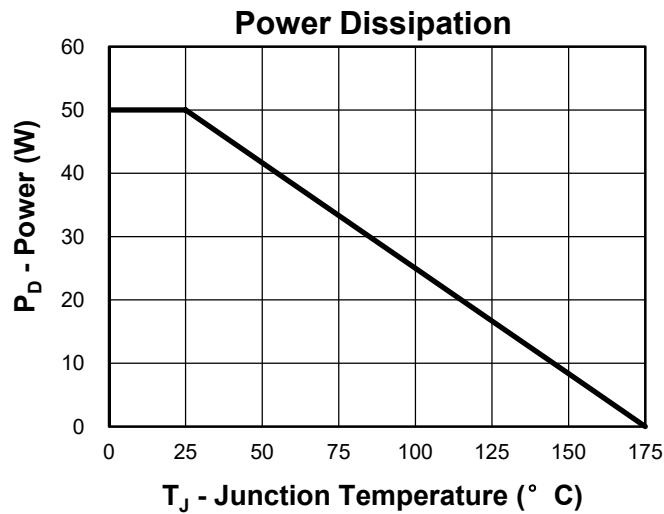


Y =Year,2017-A,2018-B,etc.

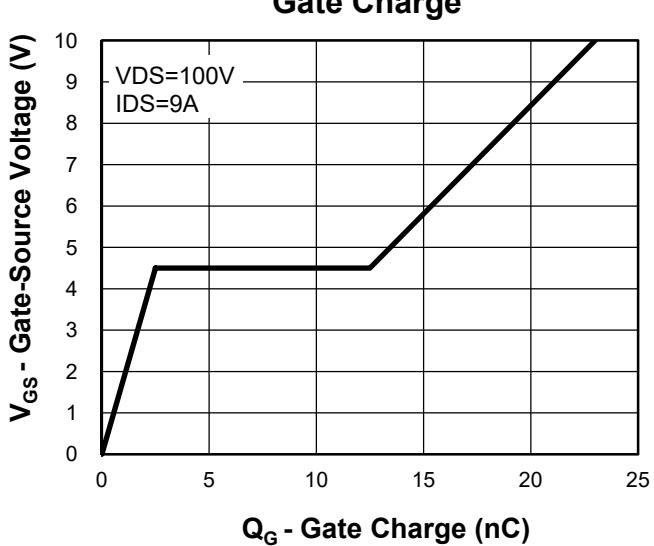
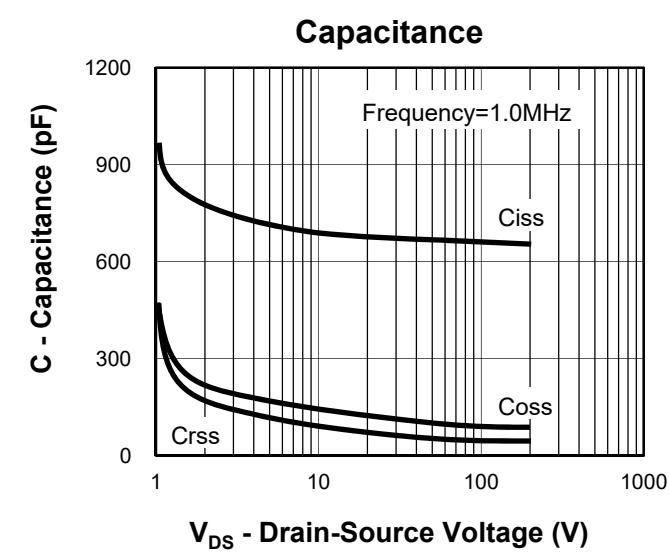
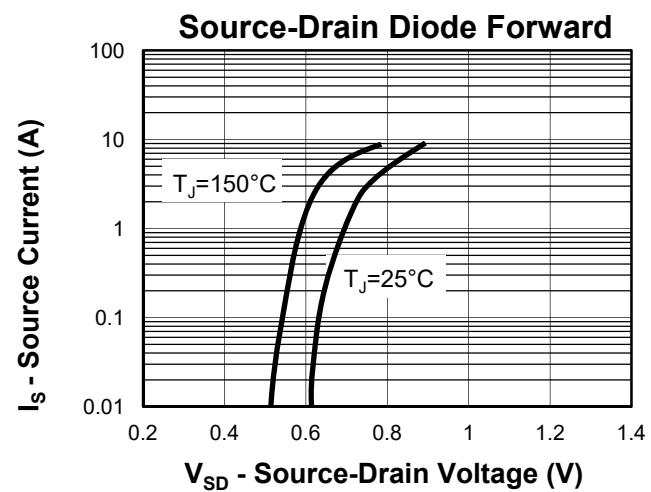
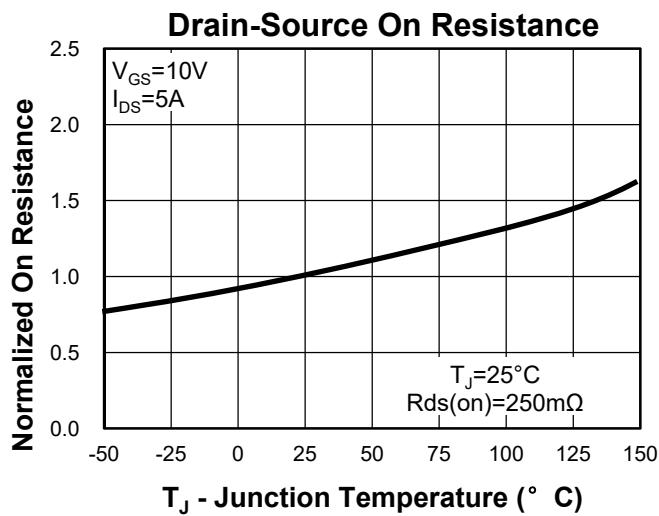
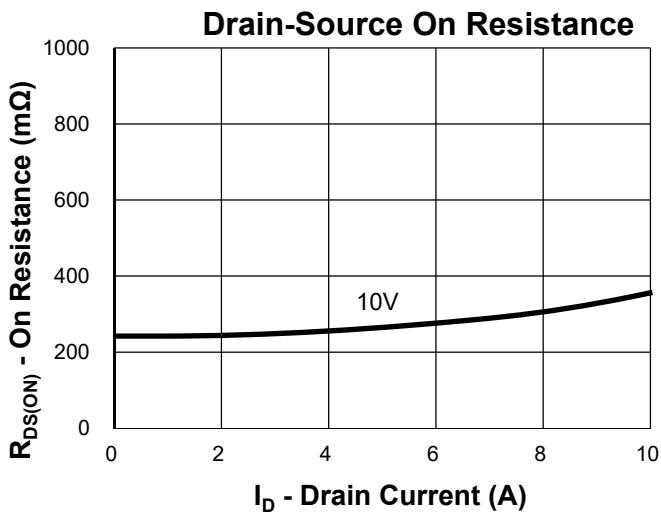
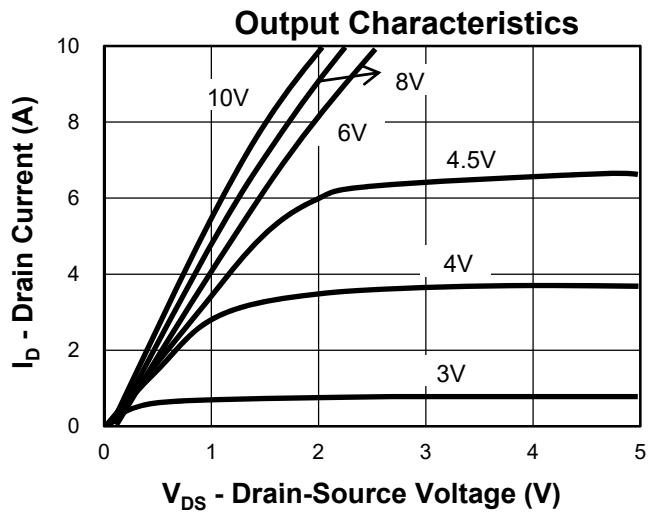
WW =Week.

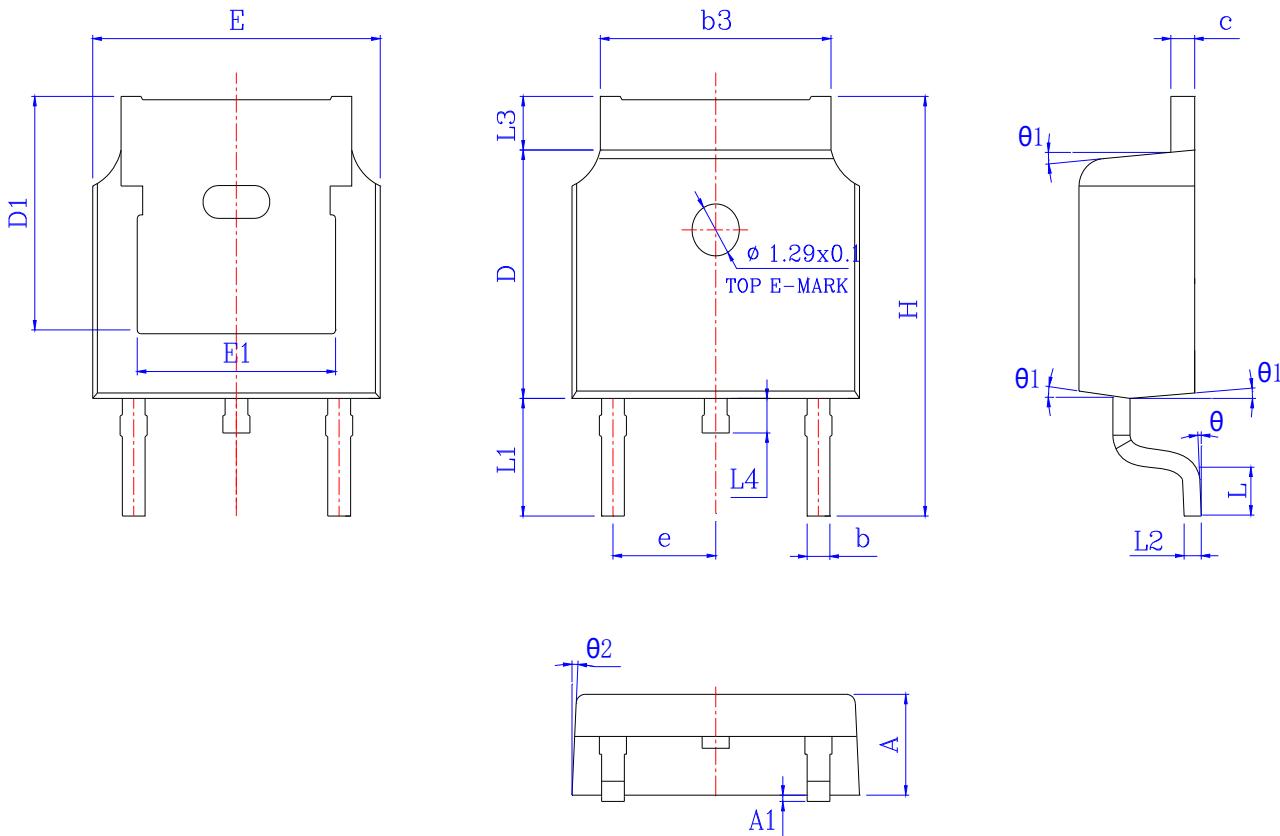
XXX =Lot number.

Typical Characteristics



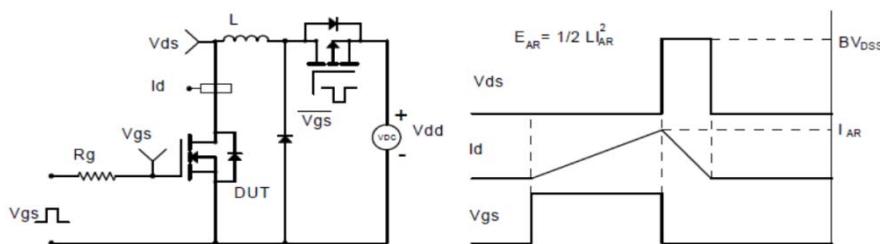
Typical Characteristics



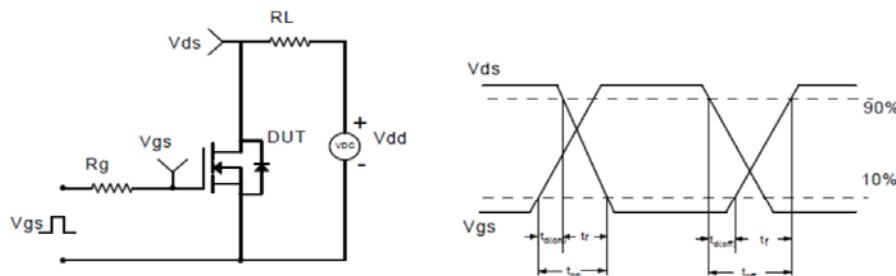
Package Information
TO-252


SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	2.200	2.300	2.400	0.087	0.091	0.094
A1	*	*	0.100	*	*	0.004
b	0.660	0.760	0.860	0.026	0.030	0.034
b3	5.130	5.295	5.460	0.202	0.208	0.215
c	0.470	0.535	0.600	0.019	0.021	0.024
D	6.000	6.100	6.200	0.236	0.240	0.244
D1	5.30 REF			0.20 REF		
E	6.500	6.600	6.700	0.256	0.260	0.264
E1	4.700	4.810	4.920	0.185	0.189	0.194
e	2.28 REF			0.09 REF		
H	9.800	10.100	10.400	0.386	0.398	0.409
L	1.400	1.550	1.700	0.055	0.061	0.067
L1	2.743 REF			0.108 REF		
L2	0.510 BSC			0.020 BSC		
L3	0.900	1.075	1.250	0.035	0.042	0.049
L4	0.600	0.800	1.000	0.024	0.031	0.039
θ	0°	*	8°	0°	*	8°
θ1	5°	7°	9°	5°	7°	9°
θ2	5°	7°	9°	5°	7°	9°

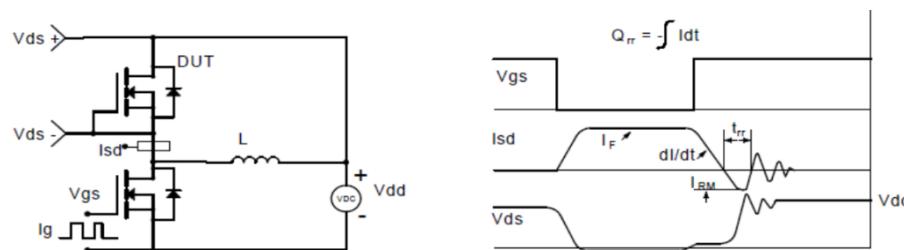
Avalanche Test Circuit and Waveforms



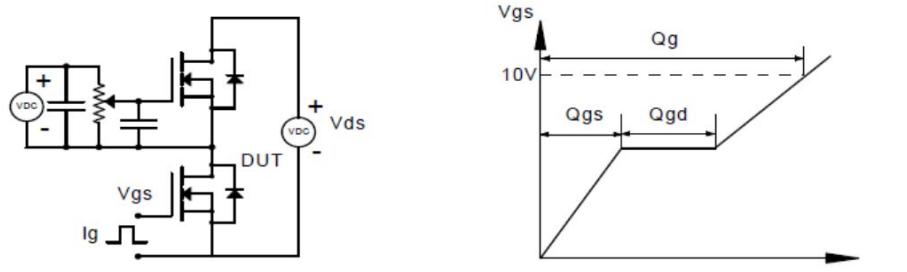
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

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